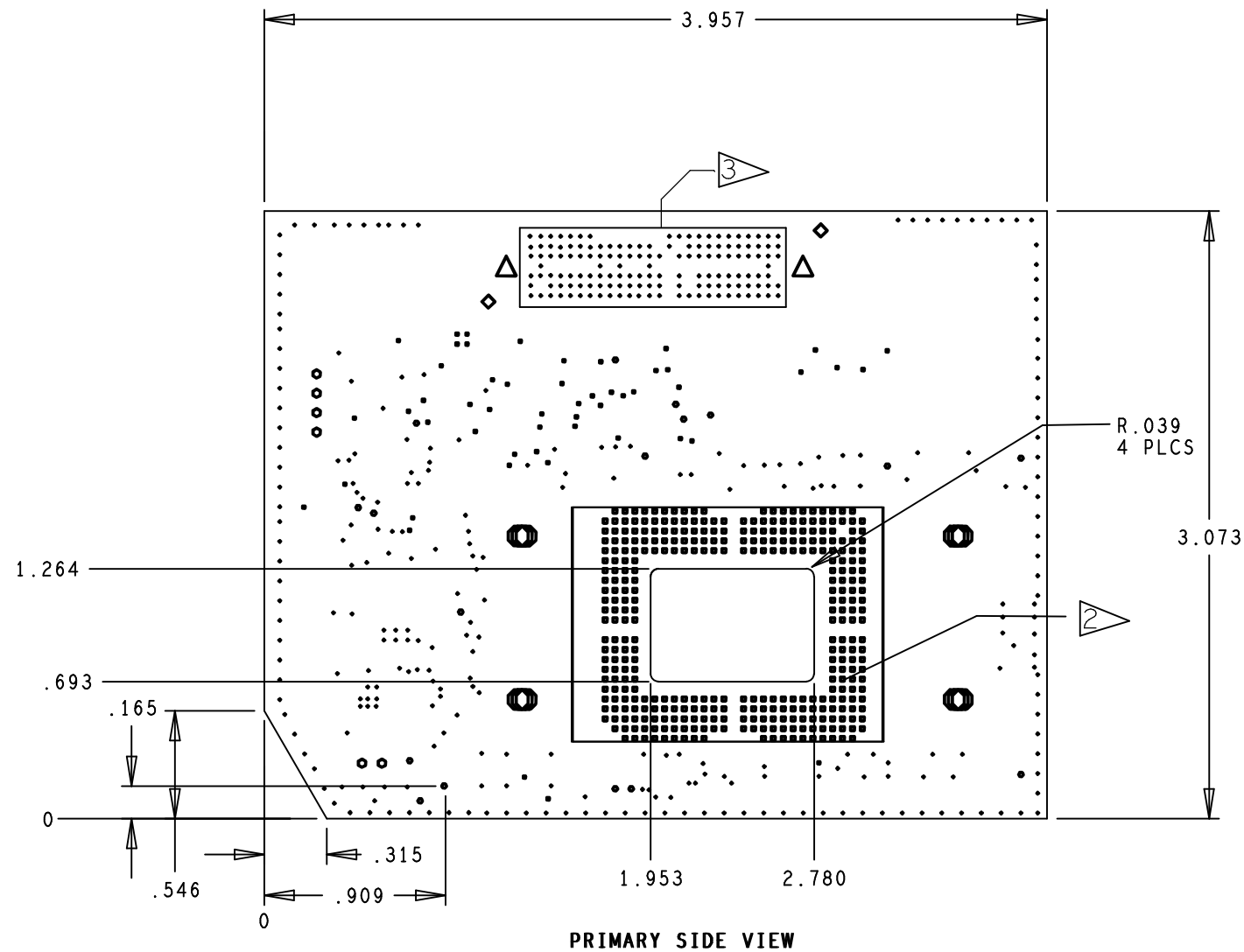


DRILL CHART: TOP & BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
■	10.0	+0.0/-0.0	PLATED	349
•	10.0	+3.0/-3.0	PLATED	412
■	12.0	+3.0/-3.0	PLATED	52
●	24.0	+3.0/-3.0	PLATED	17
○	42.0	+3.0/-3.0	PLATED	6
○	105.0	+3.0/-3.0	PLATED	12
◇	66.0	+2.0/-2.0	NON-PLATED	2
△	102.0	+3.0/-3.0	NON-PLATED	2



FAB NOTES:

1. ALL DIMENSIONS ARE IN INCHES, UNLESS OTHERWISE NOTED.
2. THE PWB SHALL BE FABRICATED TO IPC-6012, CLASS 2 AND WORKMANSHIP SHALL CONFORM TO IPC-A-600, CLASS 2. CURRENT REVISIONS.
3. BOARD MATERIAL SHALL BE 180 Tg/340 Td ISOLA FR-370HR OR EQUIVALENT, RoHS COMPLIANT AND LEAD FREE ASSEMBLY CAPABLE. BOARD MATERIAL SHALL MEET OR EXCEED IPC-4101B. COLOR: NATURAL.
4. ALL BOARDS MUST MEET OR EXCEED UL94V-0 REQUIREMENTS. PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER
5. MINIMUM COPPER WALL THICKNESS OF PLATED-THRU HOLES TO BE .001 INCH, WITH A MINIMUM ANNULAR RING OF .002 INCH.
6. OVERALL BOARD THICKNESS TO BE .062 +/- 10% AND APPLIES AFTER ALL LAMINATION AND PLATING PROCESSES, MEASURED FROM COPPER TO COPPER.
7. MAX. WARP & TWIST TO BE .0075 INCHES PER INCH.
8. BOARD MUST BE ELECTRICALLY TESTED USING SUPPLIED IPC-D-356 NETLIST.

PROCESS NOTES:

1. EXCEPT AS NOTED IN NOTE 2 AND 3, PLATE ALL EXPOSED AREAS WITH ELECTROLESS IMMERSION GOLD, NICKEL 150-200 MICROINCHES THK GOLD 5-15 MICROINCHES THK MIN.
2. PLATE INDICATED U3 PAD AREAS (350 PLACES, SECONDARY SIDE) WITH 0.00015 INCH MIN. LOW STRESS NICKEL UNDER 0.00005 - 0.000015 INCH MIN. GOLD.
3. PLATE INDICATED P1 PAD AREAS (PRIMARY AND SECONDARY SIDE) WITH ELECTROLYTIC PLATING 100-200 MICROINCHES OF NICKEL UNDER 35-50 MICROINCHES OF HARD GOLD.
4. APPLY LPI SOLDERMASK OVER BARE COPPER (SMOBC), COLOR: RED. SOLDERMASK SHALL CONFORM TO IPC-SM-840, CLASS H. CURRENT REV.
5. SOLDERMASK ARTWORK HAS ZERO (0) OVERSIZED PADS. FABRICATION VENDOR IS ALLOWED TO ADJUST THE COMPONENT SOLDERMASK PADS TO MEET THEIR TOOLING REQUIREMENTS.
6. APPLY LPI SILKSCREEN OR EQUIVALENT PER THE ARTWORK. COLOR: WHITE.

LAYER 1 PRIMARY SIDE - 1.5 OZ Cu
LAYER 2 GND PLANE - 1 OZ Cu
LAYER 3 SIGNAL - .5 OZ Cu 5/5 100 OHMS DIFFERENTIAL
5.1 50 OHM IMPEDANCE

LAYER 4 GND PLANE - 1 OZ Cu
LAYER 5 POWER PLANE - 1 OZ Cu
LAYER 6 SIGNAL - .5 OZ Cu 5/5 100 OHMS DIFFERENTIAL
5.1 50 OHM IMPEDANCE

LAYER 7 GND PLANE - 1 OZ Cu
LAYER 8 SECONDARY SIDE - 1.5 OZ Cu

IMPEDANCE TOLERANCE = +/- 10%

CUSTOMER NAME				
TEXAS INSTRUMENTS				
BOARD NAME			DESCRIPTION	
DLPLCR65EVM			FABRICATION DRAWING	
BOARD NO.	REV	DATE	PRJ#	SH 15 OF 15
DLP040	A	13 OCT 2020	DLP040	